

SOT1087-1

plastic very thin fine-pitch ball grid array package; 100 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA100
Package type industry code	VFBGA100
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	27-5-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.8	-	0.9	1	mm
A ₂	package height	0.65	-	0.7	0.75	mm
n ₂	actual quantity of termination	-	-	100	-	



2. Package outline

VFBGA100: plastic very thin fine-pitch ball grid array package; 100 balls SOT1087-1

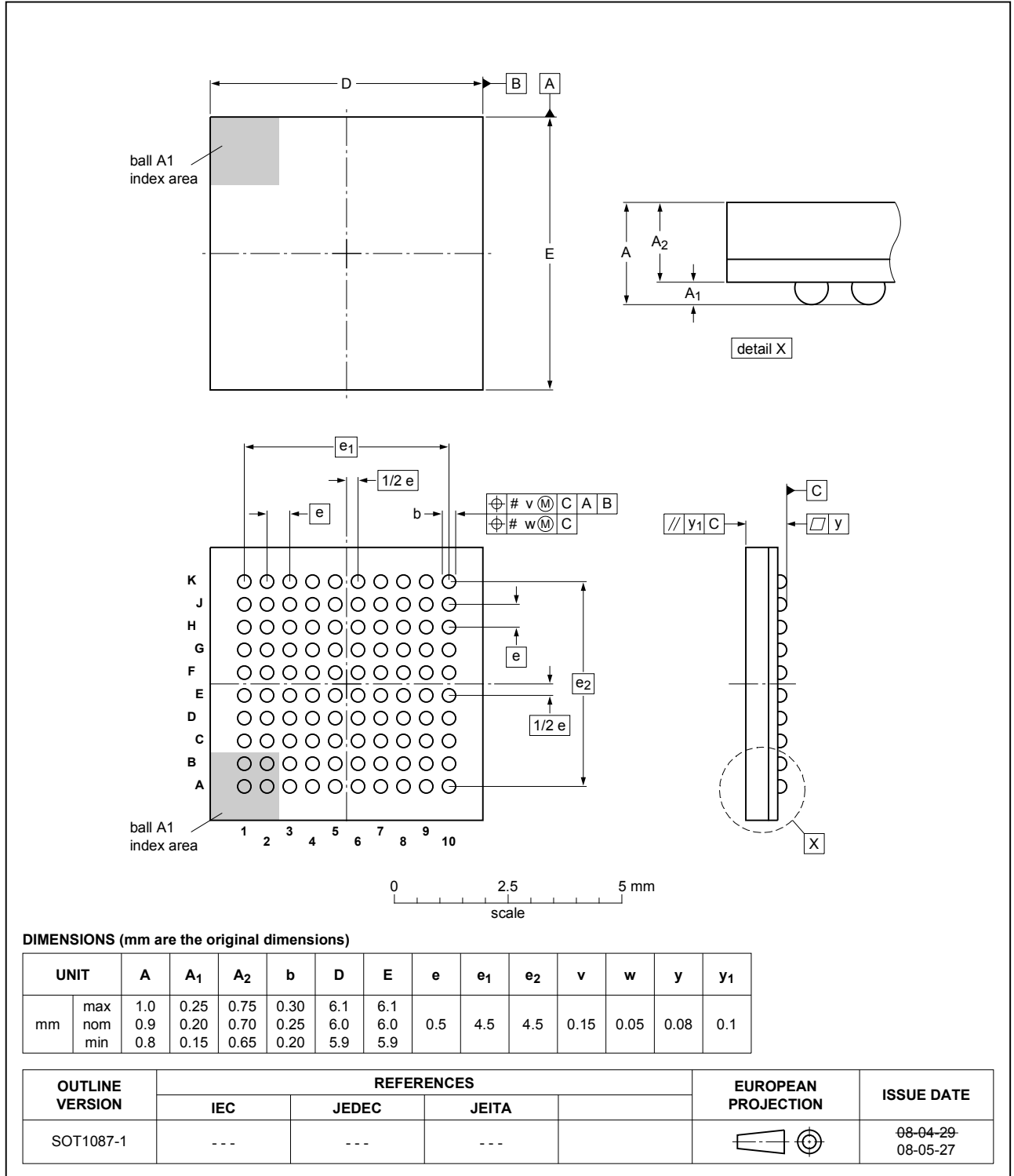


Fig. 1. Package outline VFBGA100 (SOT1087-1)

3. Soldering

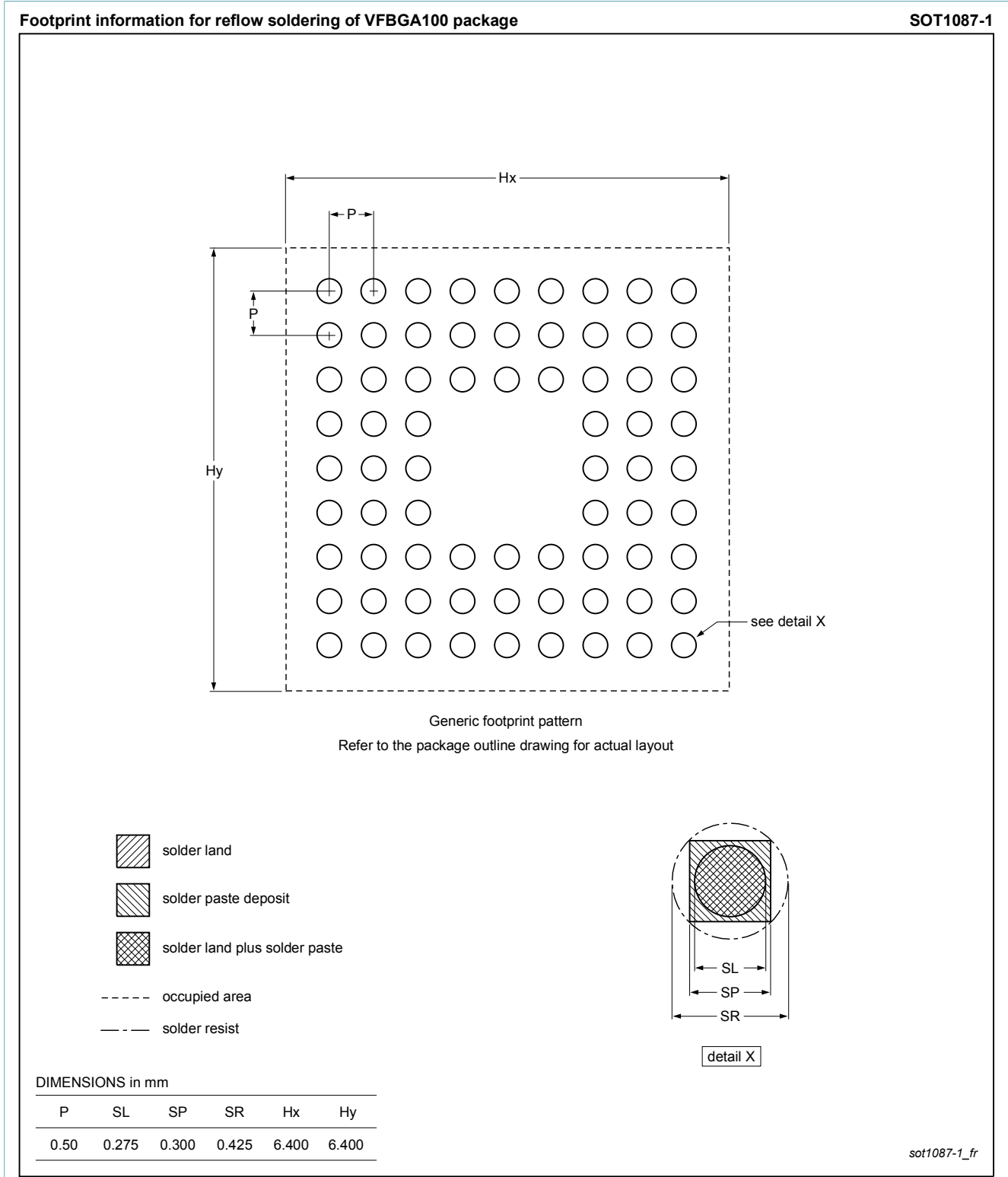


Fig. 2. Reflow soldering footprint for VFBGA100 (SOT1087-1)

4. Legal information

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